

# PATENT ASSIGNMENT

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Hideki ITO	03/01/2010
Naohisa IKEYA	03/01/2010
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NuFlare Technology, Inc.
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<b>City:</b>	Shizuoka-ken
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<b>Postal Code:</b>	410-8510
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12729926
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**PATENT**  
**REEL: 024130 FRAME: 0629**

**ASSIGNMENT**

WHEREAS I/We, the below named inventor(s), hereinafter referred to as Assignor(s), have made an invention entitled:

METHOD AND APPARATUS FOR MANUFACTURING SEMICONDUCTOR DEVICE

for which I/WE executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on \_\_\_\_\_, (Application No. \_\_\_\_\_); and

WHEREAS, NuFlare Technology, Inc.  
a corporation of Japan

whose post office address is 2068-3, Ooka Numazu-shi, Shizuoka-ken, 410-8510, Japan

(hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/WE, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. \_\_\_\_\_, filed \_\_\_\_\_) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/We have hereunto set our hand(s).

1. FULL NAME OF SOLE OR FIRST ASSIGNOR <b>Hideki ITO</b>	ASSIGNOR'S SIGNATURE <i>Hideki Ito</i>	DATE <i>March 1, 2010</i>
ADDRESS <b>c/o NuFlare Technology, Inc. 2068-3, Ooka Numazu-shi, Shizuoka-ken, 410-8510, Japan</b>		CITIZENSHIP <b>Japan</b>
2. FULL NAME OF SECOND ASSIGNOR, IF ANY <b>Naohisa IKEYA</b>	ASSIGNOR'S SIGNATURE <i>Naohisa Ikeya</i>	DATE <i>March 1, 2010</i>
ADDRESS <b>c/o NuFlare Technology, Inc. 2068-3, Ooka Numazu-shi, Shizuoka-ken, 410-8510, Japan</b>		CITIZENSHIP <b>Japan</b>